

REMARKS

Claims 46-64 remain pending in this application. Each of the pending claims is believed to define an invention that is novel and unobvious over the cited references. Favorable reconsideration of this case is respectfully requested.

Claims 46-49, 52-54 and 58-62 have been rejected under 35 U.S.C. 102(e) as being anticipated by Murayama, U.S. Patent Number 5,736,780. Murayama does not anticipate the present invention as it fails to disclose, among other things, conductive patterns formed on a surface of a base resin film that faces a main surface of a semiconductor chip.

In embodiments of the present invention, a base resin film, two is provided on a main surface of a semiconductor chip. A base resin film two has a first surface facing the main surface a semiconductor chip. Conductive patterns are formed on the first surface of the base resin film. In other words, conductive patterns are formed on the surface of the base resin film that faces the main surfaces of the semiconductor chip. The conductive patterns are formed between the first surface of the base resin film and the main surface of the semiconductor chip. Each of independent claims 46, 52, and 58 recite this feature.

In contrast, Murayama does not disclose a conductive pattern formed between the base resin film and the main surface of the semiconductor chip. Protective coding 34 of Murayama is identified in the Office Action as corresponding to the claimed based resin film. Protective coding 34 does not include a surface facing the main surface of the semiconductor chip 12. Protective coding 34 is provided on and faces a bottom or back surface of the semiconductor chip 12 as can be seen in Figures 4, 8 and 9 of Murayama. Please see column 5, line 39 – column 6, line 38 of Murayama. Accordingly, in Murayama, there is no base resin film formed on or and facing a main surface of the semiconductor chip on which electrodes are formed. In Murayama, the protective coding faces the bottom surface of the semiconductor chip 12 and the electrodes 30 are not between the protective coding 34 and the chip 12. Accordingly, Murayama defers from the claims invention and the positional relationship of the semiconductor chip and the base resin film.

In view of the above, it is clear that the cited references fail to disclose each and every elements recited in the claims as is required by 35 U.S.C. 102. Therefore, withdrawal of this rejection is respectfully requested.

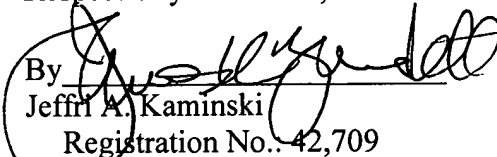
Claims 50-51, 56-57, and 63-64 have been indicates as being allowable.

If the Examiner is of the opinion that the prosecution of this application would be advanced by a personal interview, the Examiner is invited to telephone undersigned counsel to arranged for such an interview.

The Commissioner is authorized to charge any fee necessitated by this Amendment to our Deposit Account No. 220-0261.

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Respectfully submitted,

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